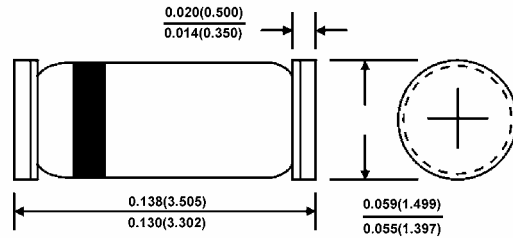




BAS85

200mW Hermetically Sealed Glass Fast Switching Schottky Barrier Diodes

MINI MELF



Dimensions in inches and (millimeters)

Features

- ✧ Low forward voltage drop
- ✧ LL-34(Mini-MELF) package
- ✧ Through-Hole device type mounting
- ✧ Hermetically sealed glass
- ✧ Compression bonded construction
- ✧ All external surfaces are corrosion resistant and terminals are readily solderable
- ✧ RoHS compliant
- ✧ Solder Hot Dip Tin (Sn) lead finish

Maximum Ratings and Electrical Characteristics

Rating at 25°C ambient temperature unless otherwise specified.

Maximum Ratings

Type Number	Symbol	Value	Units
Power Dissipation	P _d	200	mW
Repetitive Peak Reverse Voltage	V _{RRM}	30	V
Maximum DC Blocking Voltage	V _R	30	V
Average Forward Rectified Current	I _{F(AV)}	200	mA
Peak Forward Surge Current	I _{FSM}	4	A
Operating Junction Temperature	T _J	125	°C
Storage Temperature Range	T _{STG}	-65 to + 125	°C

Electrical Characteristics

Type Number	Symbol	Min	Typ	Max	Units
Breakdown Voltage I _R =10uA	B _V	30			V
Reverse Leakage Current V _R =25V	I _R			2	uA
Forward Voltage I _F =0.1mA I _F =1.0mA I _F = 10mA I _F =30mA I _F =100mA	V _F			0.24 0.32 0.40 0.50 0.80	V
Reverse Recovery Time (Note 1)	T _{rr}		5		nS
Junction Capacitance V _R =1V, f=1.0MHz	C _j			10	pF

Notes: 1. Reverse Recovery Test Conditions: I_F= I_R =10mA, R_L=100Ω, I_{RR}=1mA